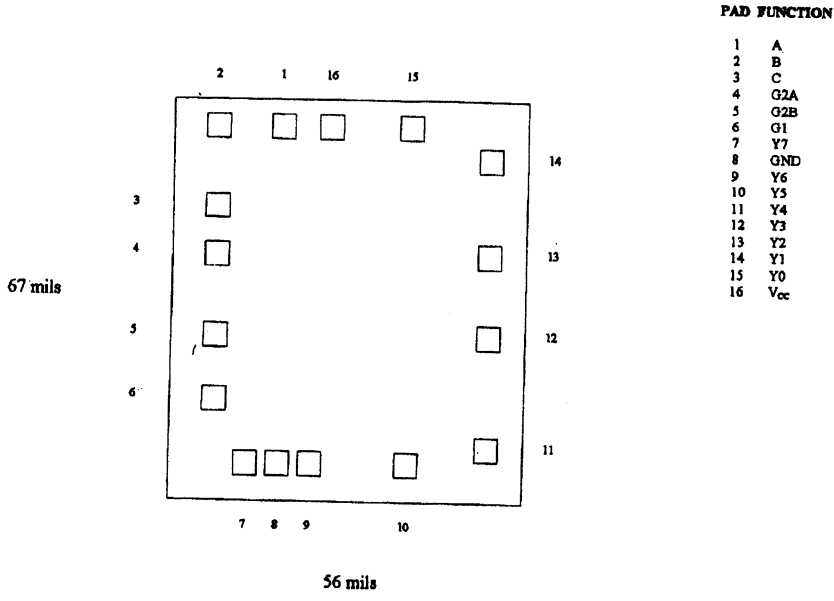




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Chip back potential is the level which bulk silicon is maintained by on-chip connection, or it is the level to which the chip back must be connected when specifically stated below. If no potential is given the chip back should be isolated.



PAD FUNCTION	
1	A
2	B
3	C
4	G2A
5	G2B
6	G1
7	Y7
8	GND
9	Y6
10	Y5
11	Y4
12	Y3
13	Y2
14	Y1
15	Y0
16	Vcc

Topside Metal: Al	Backside Metal: Si	Backside Potential:	Mask Ref.:	Bond Pads:
APPROVED BY: CW		DIE SIZE :.056" x .067"		DATE: 6/30/05
MFG: Texas Inst.		THICKNESS:		P/N: 54HC138

DG 10.1.2
 Rev B, 7/19/02